



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-28
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WB06CCV6TR	F3M2*F1618B9	A	P1C7	2024-10-28
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	107	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	6x6	48	Flat	
Comment	Package : A0BE VFQFPN 6x6x0.9 48L PITCH 0.4 8205966			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	F3M2*F1618B9		106.6302		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	7.409	mg	supplier	die	Silicon (Si)	7440-21-3		7.026	mg	948281	65892				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2455	171				
				supplier	metallization	Copper (Cu)	7440-50-8		0.163	mg	21946	1525				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.052	mg	7060	491				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	307	21				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	153	11				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5525	384				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.106	mg	14273	992				
				Glue epoxy (QMI-519)	Precious metals	1.255	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		1.004	mg	800000	9412
								supplier	Glue or tape	Methylene diacrylate polymer	42594-17-2		0.206	mg	164000	1929
supplier	Glue or tape	Epoxy resin	68475-94-5						0.031	mg	25000	294				
supplier	Glue or tape	Epoxy cyclohexylethytrimethoxysilane	3388-04-3						0.006	mg	5000	59				
SVHC	Glue or tape	Bis(α,α-dimethylbenzyl) peroxide	80-43-3						0.006	mg	5000	59				
supplier	Glue or tape	Palladium (Pd)	7440-05-3						0.001	mg	1000	12				
Bonding wire (CuPd)	Precious metals	0.345	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.341	mg	990000	3199				
				supplier	Bonding wire	Others	Proprietary		0.003	mg	10000	32				
				supplier	Molding Compound	Silica vitreous	60676-86-0		40.510	mg	880000	379910				
Encapsulation (CEL 9240ZHF10W)	M-011 Other inorganic materials	46.034	mg	supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		2.302	mg	50000	21586				
				supplier	Molding Compound	Phenolic resin	205830-20-2		1.795	mg	39000	16837				
				supplier	Molding Compound	Epoxy type resin A	Proprietary		0.921	mg	20000	8634				
				supplier	Molding Compound	Epoxy type resin B	Proprietary		0.414	mg	9000	3885				
				supplier	Molding Compound	Carbon black	1333-86-4		0.092	mg	2000	863				
				supplier	Leadframe	Copper (Cu)	7440-50-8		50.029	mg	977802	469181				
Leadframe (C194)	Copper & its alloys	51.165	mg	supplier	Leadframe	Iron (Fe)	7439-89-6		1.083	mg	21169	10158				
				supplier	Leadframe	Zinc (Zn)	7440-66-6		0.049	mg	962	461				
				supplier	Leadframe	Phosphorus (P)	7723-14-0		0.003	mg	67	32				
				supplier	Plating	Nickel (Ni)	7440-02-0		0.389	mg	918899	3647				
External Plating (Ni/Pd/Au)	M-011 Other inorganic materials	0.423	mg	supplier	Plating	Palladium (Pd)	7440-05-3		0.029	mg	69333	275				
				supplier	Plating	Gold (Au)	7440-57-5		0.005	mg	11768	47				